AMENDMENTS TO THE CLAIMS

1. (Previously Presented) A method of manufacturing a probe unit having leads whose front portions extending beyond an edge of a substrate, the method comprising the steps of:

forming a recess in a surface layer of a substrate;

forming a sacrificial layer in the recess;

forming a number of leads on the surface of the substrate, the leads being disposed in parallel and extending into an area of the sacrificial layer;

forming a cut extending from a bottom surface of the substrate into the sacrificial layer; and

removing the sacrificial layer.

2. (Original) A method according to claim 1, wherein the sacrificial layer is made of metal, resin or inorganic material.

3. (Original) A method of manufacturing a probe unit having leads whose front portions extending beyond an edge of a substrate, the method comprising the steps of:

forming a through hole through a substrate;

filling a sacrificial layer in the through hole;

forming a number of leads on the surface of the substrate, the leads being disposed in parallel and extending into an area of the sacrificial layer; and

removing the sacrificial layer.

4. (Original) A method according to claim 3, wherein the sacrificial layer is made of metal, resin or inorganic material.

5. (Original) A method of manufacturing a probe unit having leads whose front portions extending beyond an edge of a substrate, the method comprising the steps of:

(a) applying a ultraviolet ray to a partial surface area of a photosensitive etching glass substrate;

(b) forming a number of leads on the surface of the substrate, the leads being disposed in parallel and extending from a ultraviolet ray unradiated area into a ultraviolet ray radiated area; and

(c) etching the glass substrate in the ultraviolet ray radiated area.

6. (Original) A method according to claim 5, further comprising, before said step (b), the steps of:

(x) applying a ultraviolet ray to areas over which the leads are to be formed in an area where the ultraviolet ray is not radiated, and etching the irradiated areas to form through holes; and

(y) filling the through holes with conductive members.

7. (Currently Amended) A method of manufacturing a probe unit, said method comprising:

forming a plurality of parallel, elongated leads on the contiguous flat surfaces of a substrate and a sacrificial layer, the sacrificial layer having different etching characteristics then those of said substrate, said leads extending over both portions of said substrate and portions of said sacrificial layer;

etching said sacrificial layer so that said leads include a supported portion located on said substrate and an unsupported portion extending over at least one edge of said substrate.

8. (Previously Presented) The method of claim 7, further including forming said sacrificial layer in said substrate before said depositing step.

9. (Currently Presented) The method of claim 8, further including forming a depression in said substrate and forming said sacrificial layer having a top surface co-planar with that of the substrate in said depression.

10. (Previously Presented) The method of claim 9, further including removing a portion of said substrate located below said depression.

11. (Previously Presented) The method of claim 7, further including forming an opening in said substrate and forming said sacrificial layer in said opening before said depositing step.

12. (Previously Presented) The method of claim 11, wherein said sacrificial layer is formed by filling said opening with an excess amount of sacrificial material and removing excess sacrificial material to ensure that said flat surface is defined.

13. (Previously Presented) The method of claim 7, further including removing a portion of said substrate surrounding a portion of said opening.

14. (Previously Presented) The method of claim 7, wherein said substrate and said sacrificial layer are formed of the same material and said sacrificial layer is treated to have different characteristics than said substrate.

15. (Previously Presented) The method of claim 14, wherein said substrate and said sacrificial layers are made from a photosensitive etching material and the area corresponding to said sacrificial layer are irradiated.

16. (Previously Presented) The method of claim 15, wherein said area corresponding to said sacrificial material are irradiated with ultra violet radiation.

17. (Currently amended). A method of manufacturing a probe unit having leads supported on a top surface of a substrate, the method comprising:

forming a sacrificial layer having a top surface which is contiguous to a top surface of the substrate, the sacrificial layer being made of a material which is different than the material of the substrate;

forming a number of parallel leads on the top surface of the substrate and an area of the sacrificial layer; and

removing the sacrificial layer.

18. (Previously Presented) A method according to claim 1, wherein the sacrificial layer forming step, comprises:

depositing the sacrificial layer both in the recess and on a surface of the substrate surrounding the recess; and

removing part of the sacrificial layer to leave the sacrificial layer in the recess.

19. (Previously Presented) A method according to claim 18, wherein the sacrificial layer is first deposited on the entire upper surface of the substrate surrounding the recess and then all of the sacrificial layer located outside of the recess is removed.